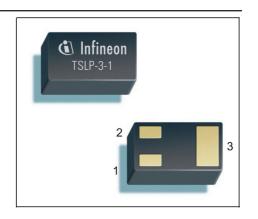


Low Noise Silicon Bipolar RF Transistor

- Low voltage/ Low current operation
- Transition frequency of 14 GHz
- High insertion gain
- Ideal for low current amplifiers and oscillators
- Pb-free (RoHS compliant) and halogen-free thin small leadless package
- Qualification report according to AEC-Q101 available







ESD (Electrostatic discharge) sensitive device, observe handling precaution!

Туре	Marking	Pin Configuration			Package
BFR340L3	FA	1 = B	2 = E	3 = C	TSLP-3-1

Maximum Ratings at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Value	Unit
Collector-emitter voltage	$V_{\sf CEO}$	6	V
Collector-emitter voltage	V_{CES}	15	
Collector-base voltage	V_{CBO}	15	
Emitter-base voltage	V_{EBO}	2	
Collector current	I _C	10	mA
Base current	l _B	2	
Total power dissipation ¹⁾	P _{tot}	60	mW
_ <i>T</i> _S ≤ 120°C			
Junction temperature	T_{J}	150	°C
Storage temperature	T _{Stq}	-55 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ²⁾	R _{thJS}	500	K/W

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 $^{{}^{1}}T_{\rm S}$ is measured on the collector lead at the soldering point to the pcb

 $^{^2}$ For the definition of R_{thJS} please refer to Application Note AN077 (Thermal Resistance Calculation)



Electrical Characteristics at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage	V _{(BR)CEO}	6	9	-	V
$I_{\rm C}$ = 1 mA, $I_{\rm B}$ = 0					
Collector-emitter cutoff current	I _{CES}	-	-	10	μA
$V_{CE} = 15 \text{ V}, V_{BE} = 0$					
Collector-base cutoff current	I _{CBO}	-	-	100	nA
$V_{\text{CB}} = 5 \text{ V}, I_{\text{E}} = 0$					
Emitter-base cutoff current	I _{EBO}	-	-	1	μA
$V_{\rm EB}$ = 1 V, $I_{\rm C}$ = 0					
DC current gain	h _{FE}	90	120	160	-
$I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 3 V, pulse measured					



Electrical Characteristics at T_A = 25 °C, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics (verified by random sampling	ıg)		1	1	_
Transition frequency	f _T	10	14	-	GHz
$I_{\rm C}$ = 6 mA, $V_{\rm CE}$ = 3 V, f = 1 GHz					
Collector-base capacitance	C _{cb}	-	0.17	0.4	pF
$V_{\text{CB}} = 5 \text{ V}, f = 1 \text{ MHz}, V_{\text{BE}} = 0 ,$					
emitter grounded					
Collector emitter capacitance	C _{ce}	-	0.13	-	
$V_{CE} = 5 \text{ V}, f = 1 \text{ MHz}, V_{BE} = 0$,					
base grounded					
Emitter-base capacitance	C _{eb}	-	0.12	-	
$V_{\text{EB}} = 0.5 \text{ V}, f = 1 \text{ MHz}, V_{\text{CB}} = 0$,					
collector grounded					
Minimum noise figure	NF _{min}	-	1.15	-	dB
$I_{\rm C}$ = 1 mA, $V_{\rm CE}$ = 3 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$, f = 1.8 GHz					
Power gain, maximum stable ¹⁾	G _{ms}	-	17.5	-	-
$I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 3 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$,					
$Z_{L} = Z_{Lopt}$, $f = 1.8 \text{ GHz}$					
Power gain, maximum available ¹⁾	G _{ma}	-	13	-	dB
$I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 3 V, $Z_{\rm S}$ = $Z_{\rm Sopt}$,					
$Z_{L} = Z_{Lopt}$, $f = 3 \text{ GHz}$					
Transducer gain	S _{21e} ²				dB
$I_{\rm C}$ = 5 mA, $V_{\rm CE}$ = 3 V, $Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω ,					
f = 1.8 GHz		_	14	-	
f = 3 GHz		_	10	-	
Third order intercept point at output ²⁾	IP3	-	12.5	-	dBm
$V_{CE} = 3 \text{ V}, I_{C} = 5 \text{ mA}, f = 1.8 \text{ GHz},$					
$Z_{\rm S} = Z_{\rm L} = 50\Omega$					
1dB compression point at output	P _{-1dB}	-	-1	-	1
$I_{\rm C} = 5 \text{ mA}, V_{\rm CE} = 3 \text{ V}, Z_{\rm S} = Z_{\rm L} = 50\Omega$.32				
f = 1.8 GHz					
			ļ	L	

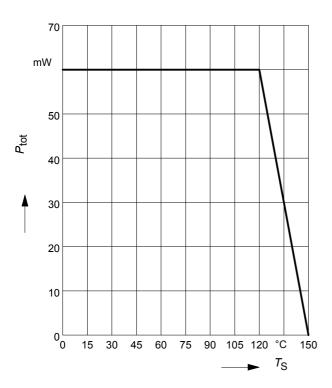
 $^{^{1}}G_{\text{ma}} = |S_{21e} / S_{12e}| \text{ (k-(k^2-1)}^{1/2}), \ G_{\text{ms}} = |S_{21e} / S_{12e}|$

²IP3 value depends on termination of all intermodulation frequency components.

Termination used for this measurement is 50Ω from 0.1 MHz to 6 GHz



Total power dissipation $P_{tot} = f(T_S)$

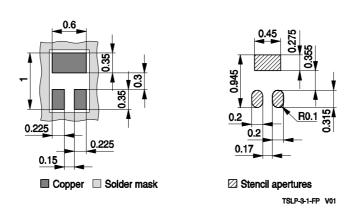


TSLP-3-1-PO V03



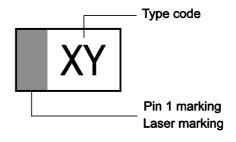
Pin 1 marking Top view Bottom view 0.05 MAX. 0.05 M

Foot Print



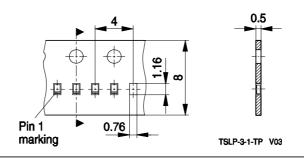
1) Dimension applies to plated terminal

Marking Layout (Example)



Standard Packing

Reel Ø 330 mm: 15.000 Pieces/ Reel



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Edition 2009-11-16

Published by Infineon Technologies AG 81726 Munich, Germany

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